

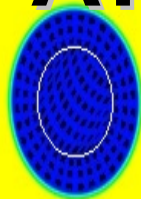
TEMPERATURES
URE Scalar Unaveraged Top shell
56E-05 Celsius Max: 1.92E+01 Celsius
ordinate System

ATLAS Upgrade

DESY activities

Marcel Stanitzki

DESY ATLAS Upgrade group





Introduction

- DESY ATLAS Upgrade activities focus on silicon tracking
- Flagship project
 - Strip Endcap Upgrade (2022)
 - Petal 2014 R&D project as milestone
- Also some involvement in the IBL (2013)
- Building on infrastructure and expertise available at DESY
- Close collaboration with CMS Upgrade Projects at DESY



Current SCT activities



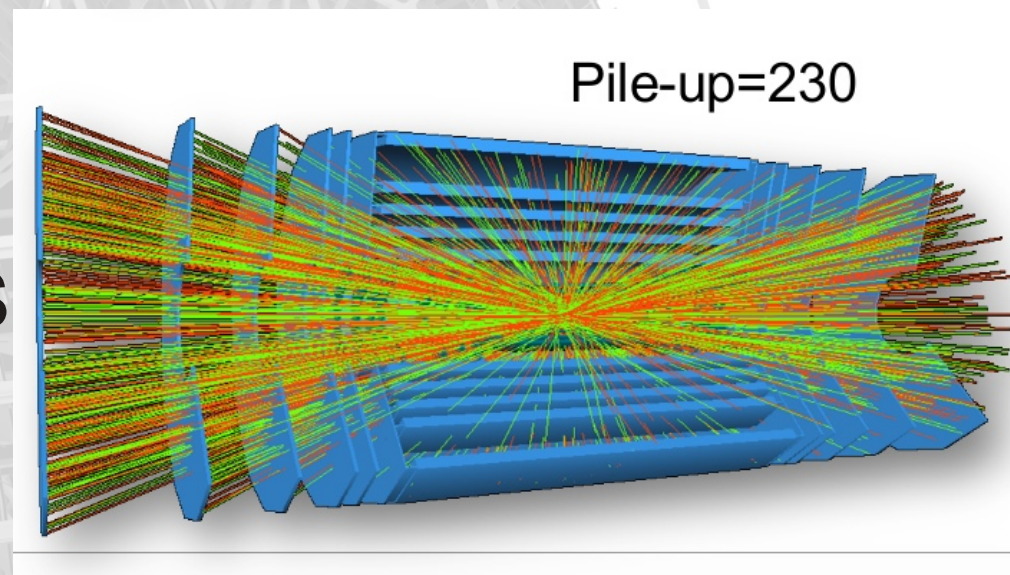
- DESY is member of the SCT collaboration
 - Since November 2011
- Working on
 - Offline Calibration
 - Long-Term Monitoring
 - Radiation Damage Studies
- Invaluable experience for the Upgrade project



Challenges in the Upgrade



- HL-LHC machine challenges
 - Higher track density
 - Many more pile-up events
- This means for the ATLAS Inner Detector
 - Finer granularity
 - Less material
 - Even more rad-hard
- New design ideas

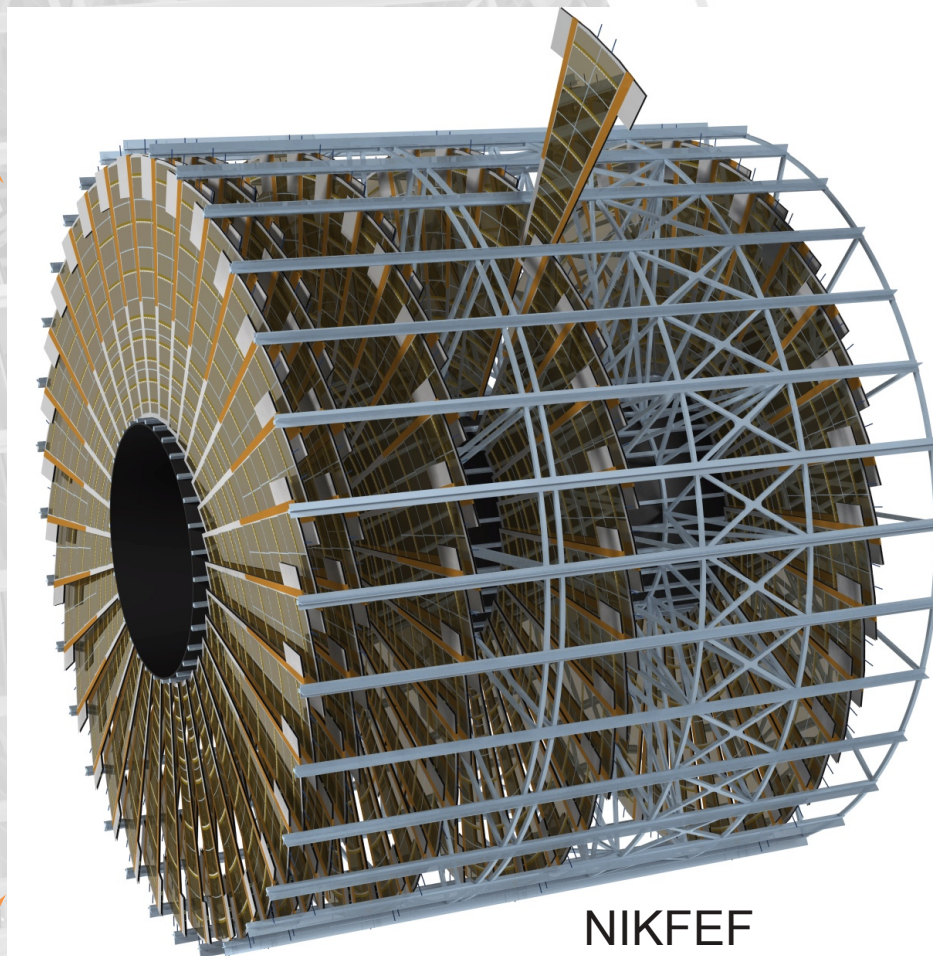




The Strip Endcap Upgrade

- Current SCT (Silicon Strip Tracker) will reach end-of-life in 2022
- Upgrade to handle higher event rates, pile-up and radiation levels from the High-Luminosity LHC
- Endcaps
 - 10 disks with 32 Petals each
 - 9 modules per Petal
 - 25 m² Silicon

2 m

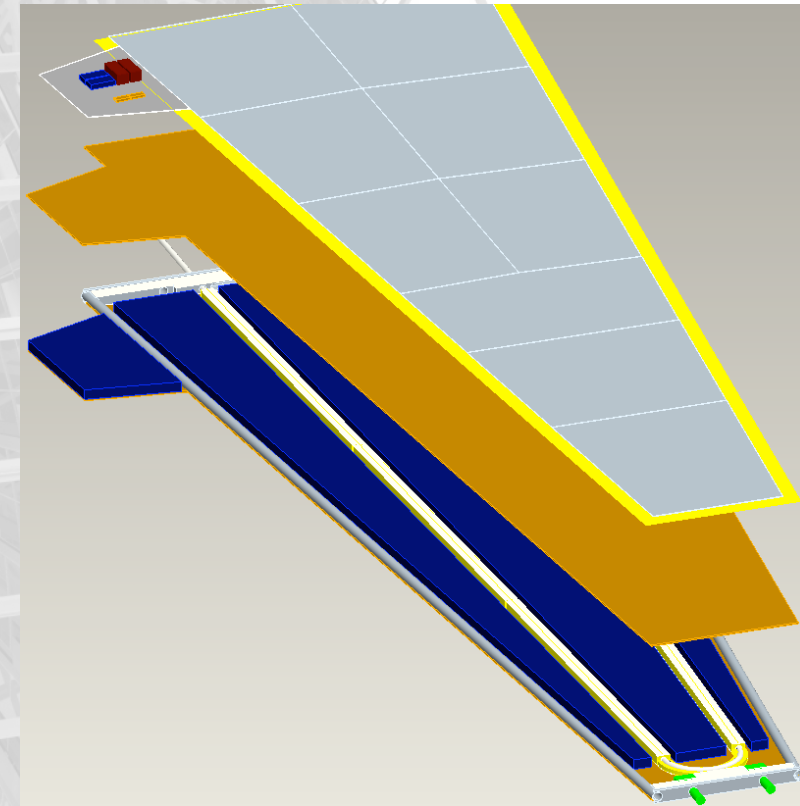




DESY Activities in the Strip Upgrade project



- Module Construction
 - Barrel & Endcap
- Endcap Mechanics
 - Study new materials, FEA studies, cooling, mechanical structures
- End-of-substructure electronics
 - Barrel & Endcap
- Testing & System integration
- Upgrade simulation
- Test beam

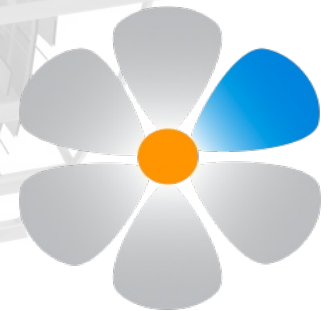
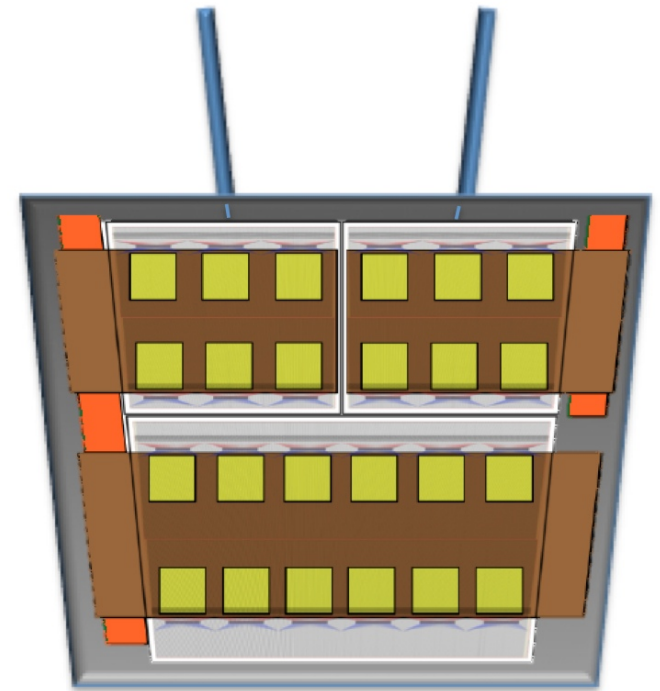




From Petalets to Petals to an Endcap



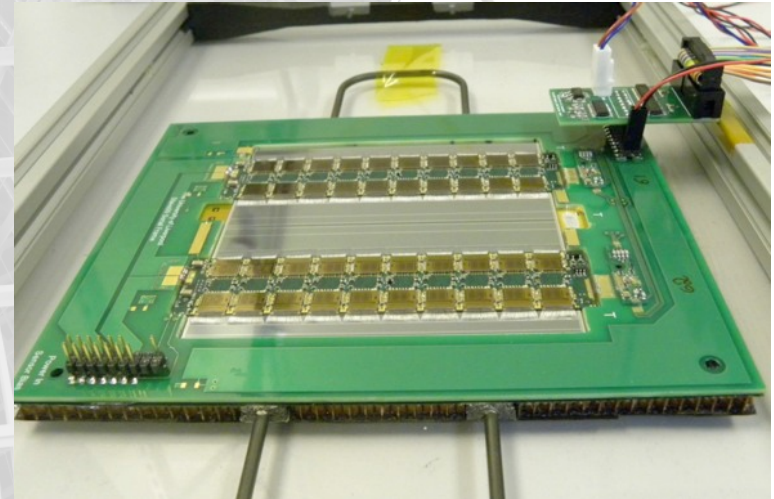
- Petalet 2012
 - Construction of Petalets
 - First step towards a full-size Petal
 - DESY is key player in this
- PETAL 2014
 - Build full-size prototypes
 - Complete with services, cooling ...
- Silicon Strip Endcap
 - Installation in 2021/22



PETAL2014.

Module Construction

- Currently
 - Modules for Barrel Staves
 - Gluing, Bonding & Testing
 - Build up expertise
- From summer onwards
 - Making Petalet modules
 - Preparing for Petal production



Mechanical studies

- DESY will assemble a full end-cap for Phase 2
 - Petal design and construction is the first milestone
 - New materials under investigation (cooperation with CMS)
 - Petalet as a first step
 - To be build in 2012
- Studies include
 - Finite Element Analysis (FEA)
 - Thermal measurements of prototypes



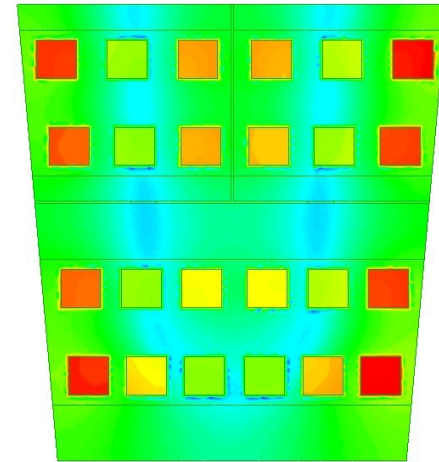


FEA Simulations

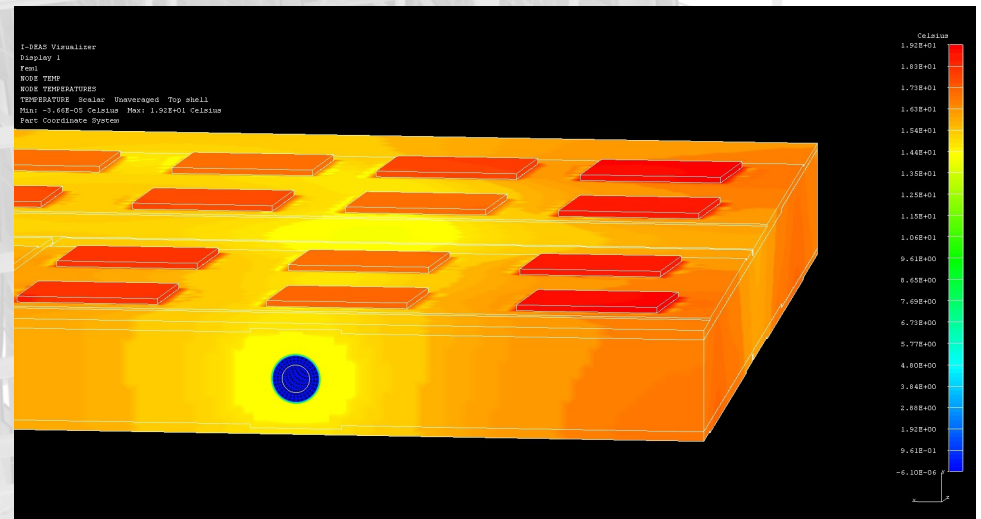


- Using FEA to
 - Simulate heat load
 - Optimize cooling
 - Distribution of chips
 - Studying new materials
- Input to
 - Petalet design
 - Petal design

```
Display 1  
Shell_1  
3 - NODE TEMP  
NODE TEMPERATURES  
TEMPERATURE Scalar Unaveraged Top shell  
Min: -9.85E-01 Celsius Max: 5.13E+00 Celsius  
Part Coordinate System
```



Celsius
5.13E+00
4.83E+00
4.52E+00
4.22E+00
3.91E+00
3.60E+00
3.30E+00
2.99E+00
2.69E+00
2.38E+00
2.07E+00
1.77E+00
1.46E+00
1.16E+00
8.50E-01
5.45E-01
2.39E-01
-6.73E-02
-3.73E-01
-6.79E-01
-9.85E-01



```
1-DESS Visualizer  
Display 1  
Fem1  
NODE TEMP  
NODE TEMPERATURES  
TEMPERATURE Scalar Unaveraged Top shell  
Min: -5.44E-05 Celsius Max: 1.92E+01 Celsius  
Part Coordinate System
```

Celsius
1.92E+01
1.82E+01
1.73E+01
1.62E+01
1.54E+01
1.44E+01
1.35E+01
1.25E+01
1.15E+01
1.04E+01
9.61E+00
8.65E+00
7.69E+00
6.73E+00
5.77E+00
4.80E+00
3.84E+00
2.88E+00
1.92E+00
9.61E-01
-6.10E-04

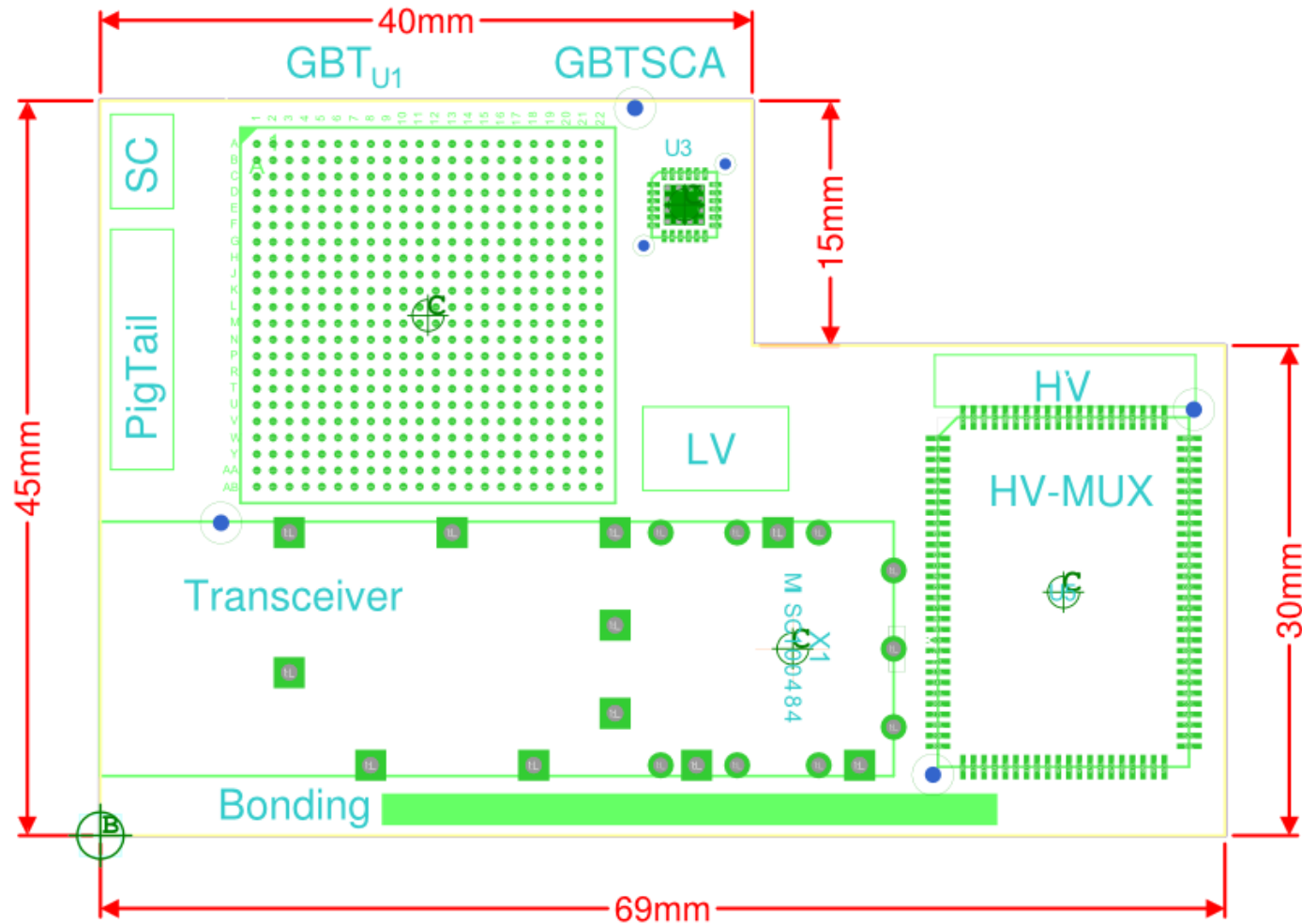


End-of-substructure electronics



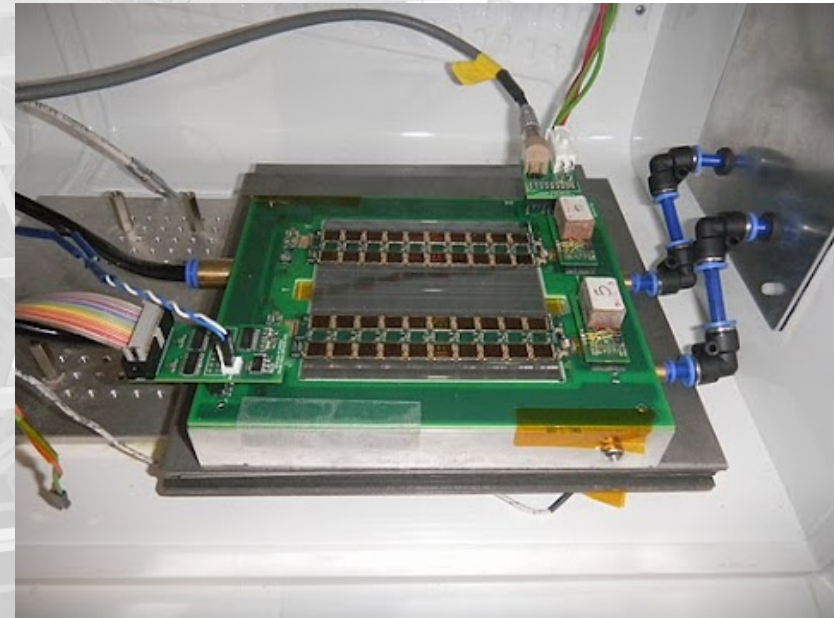
- Connects a strip detector unit to the outside world
 - High-speed optical data links
 - Power distribution
 - Slow controls
- Common schematics
 - Different layouts for Barrel and Endcap due to mechanical constraints
- DESY driven effort

First drawings



HSIO Teststands

- HSIO = High-Speed IO board
- Currently testing
 - Individual hybrids
 - complete modules
- Moving to bigger units soon
 - Stavelets
 - Petalets
- Final goal
 - Testing entire Petalets

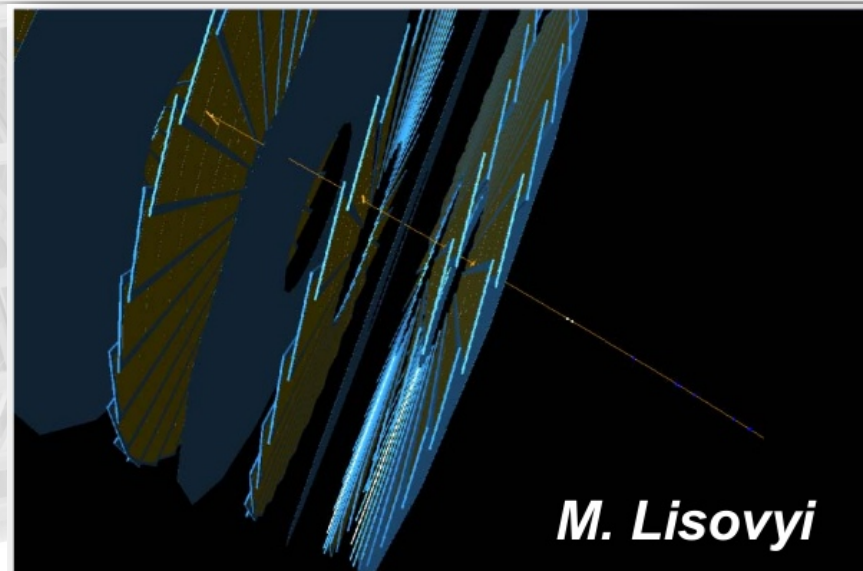
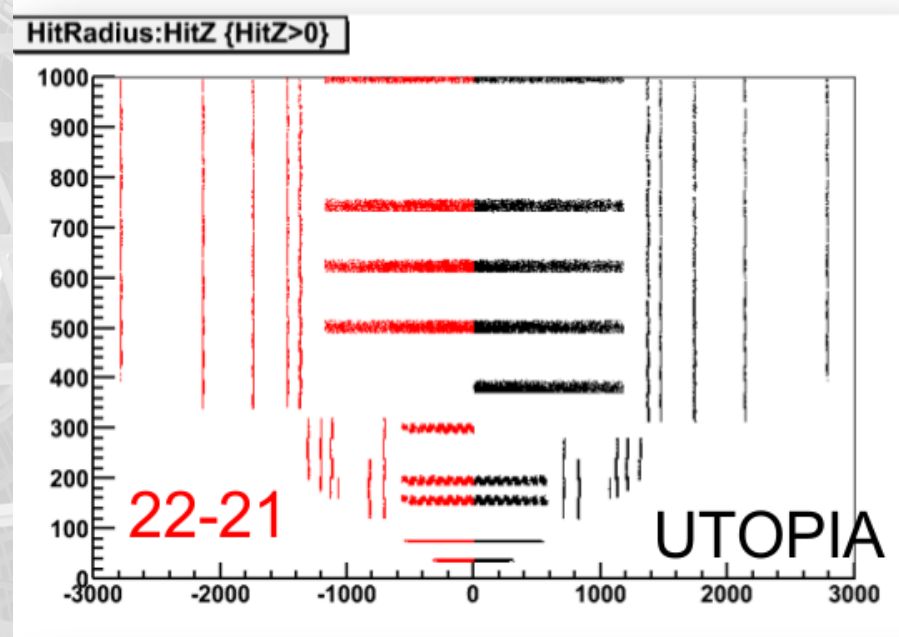




Upgrade Simulation

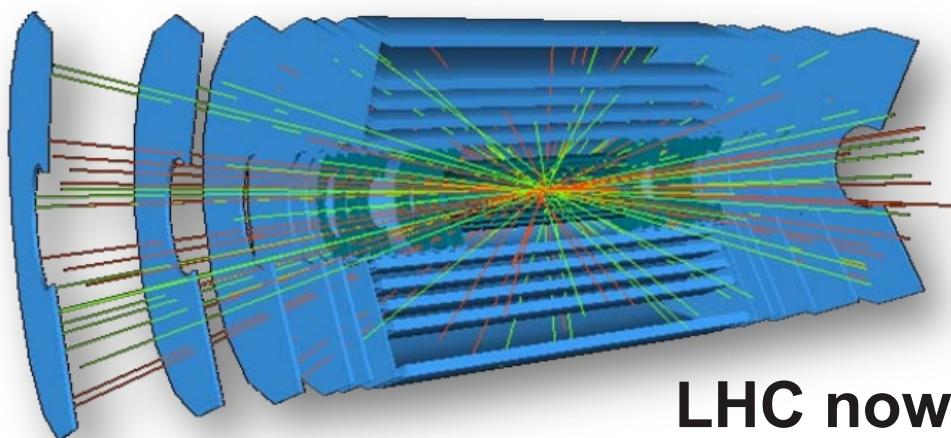


- DESY has leading role
- Study detector layouts
 - Tracking efficiencies
 - Material budgets
 - B-tagging
 - Pile-up
- Detailed Endcap Modelling
- Essential input to the detector design



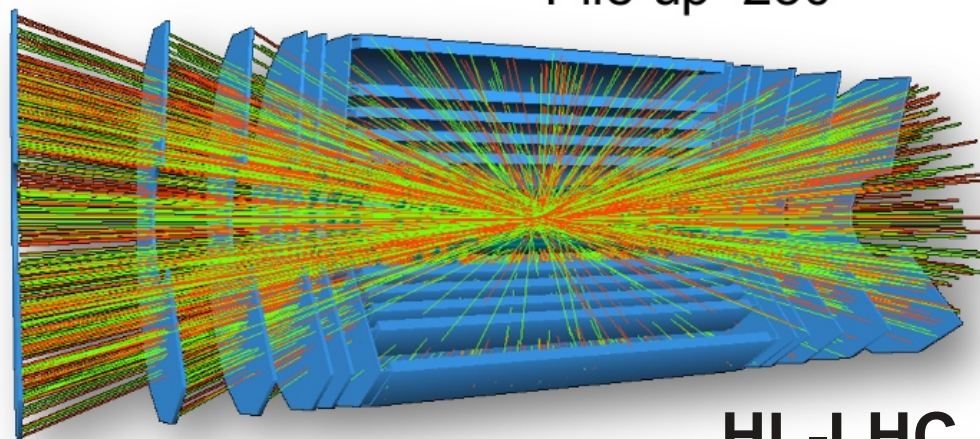
Studying pile-up, tracking, b-tagging

Pile-up=23

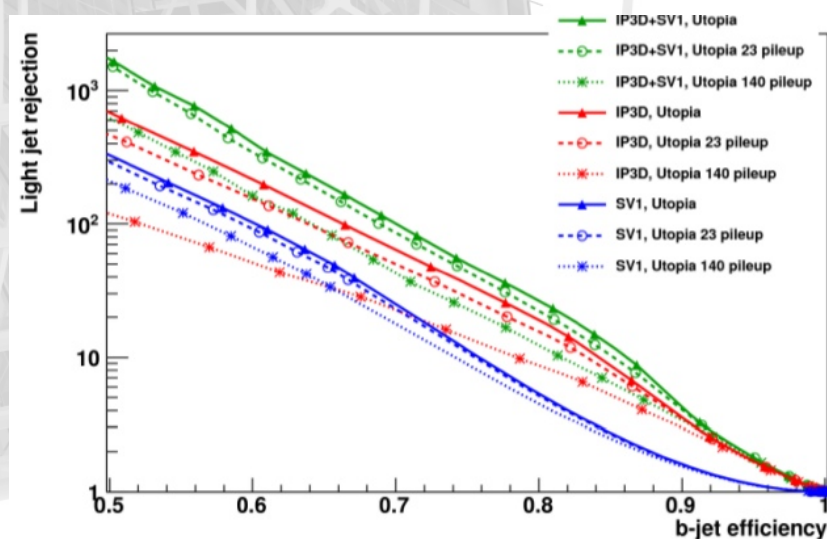
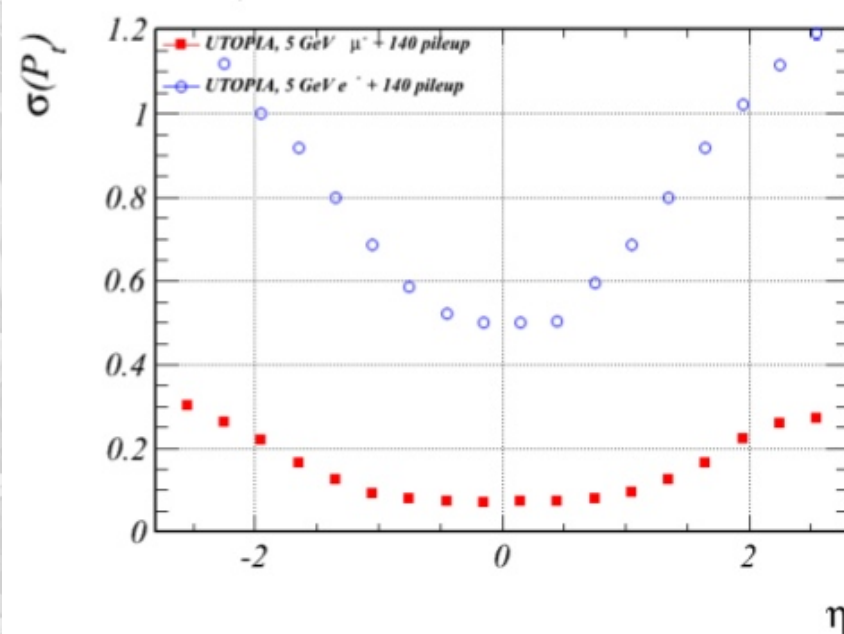


LHC now

Pile-up=230

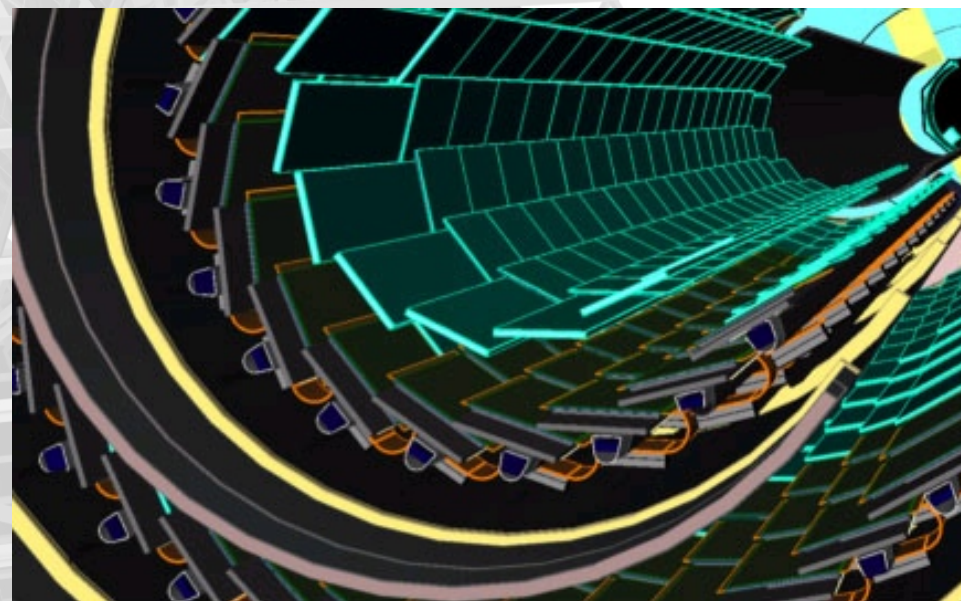


HL-LHC



Other Upgrade Activities

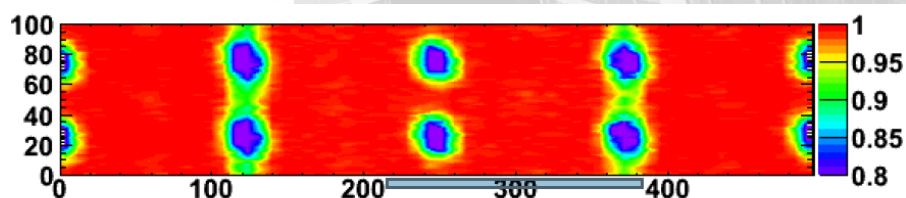
- DESY has small involvement in IBL
 - Mainly test beam support
 - Telescope, Reconstruction...
- Implementing Charge sharing models
- Optical fibers for the readout
 - Procurement and testing
- Test beam telescopes
 - Rates up to 4 kHz possible



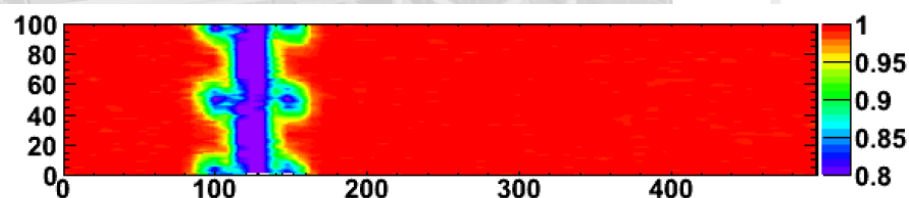
Test beam analysis

- Major player in the IBL test beam analysis
 - Making use of EUDET Software infrastructure
- Results from input to sensor decision for the IBL

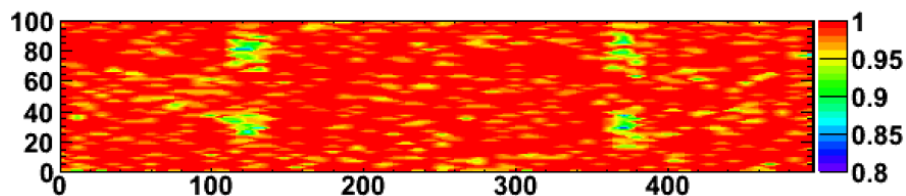
ATLAS IBL



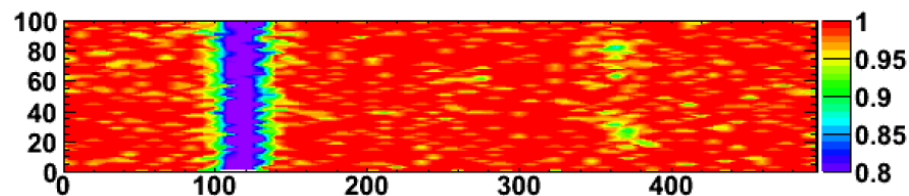
(a) CNM-3D, 0 degree, n-irrad HV=160V, Eff.=97.46%



(b) PPS, 0 degree, n-irrad, HV=1000V, Eff.=97.90%



(c) CNM-3D, 15 degree, p-irrad, HV=160V, Eff.=98.96%



(d) PPS, 15 degree, p-irrad, HV=940V, Eff.=97.65%



Areas of (potential) cooperation



- Sensor R&D, evaluation and procurement
 - Utilizing close KEK ties to Hamamatsu
 - Test beams
 - DESY Test beam as a facility for Detector R&D
 - Explore Novel materials
 - Needed for ultra-low mass structures
 - Sharing experiences, vendors ...
 - Electronics design
 - Share designs and experience (e.g. EoS card)
 - DAQ for generic sensor development
 - Using e.g. KEK's Universal DAQ module
 - Many Points are generic and extend beyond the ATLAS upgrade scope
- Already working together
- Potential for cooperation



Summary



- DESY ATLAS group
 - Focus on silicon strip tracking
 - Endcap Upgrade is main project
- Some small involvements in other project
- Cooperation with KEK
 - Some activities already happening
 - Potential for more activities
 - Many aspects generic, beyond ATLAS, CMS ...